Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product Information in this Catalog

Product information in this catalog is as of January 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *²

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
 (2) Million
- (6) Military equipment
- Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.

TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ ME-H SERIES)

PARTS NUMB	ER	*	Operating Tem	p.:-40~+125°C(Including self-generated heat)
M E K			∆=B	lank space
①Series name		(5	Nominal induct	ance
Code ME	Series name Metal Wire-wound Chip Power Inductor		Code (example)	Nominal inductance [μ H]
			R47	0.47
②Dimensions(T))		1R0	1.0
Code	Dimensions (T) [mm]		2R2	2.2
НК	0.8	*	R=Decimal po	vint
KK	1.0			
		6	Inductance tol	erance
③Dimensions(L)	×W)		Code	Inductance tolerance
Code	Dimensions $(L \times W)$ [mm]		М	±20%
2012	2.0 × 1.2			
2016	2.0 × 1.6	(7	Special code	
2520	2.5 × 2.0		Code	Special code
			\bigtriangleup	Standard
④Packaging				
Code	Packaging	8	Internal code	
Н	Taping(special specification)			

STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY



Recommended Land Patterns

Surface Mounting

•Mounting and soldering conditions should be checked beforehand.

•Applicable soldering process to these products is reflow soldering only.

		1
A	В В	A

l1	Туре	A	В	С
с	2012	0.7	0.8	1.4
_	2016	0.7	0.8	1.8
A	2520	0.9	1.0	2.2
				Unit · mm

Туре	L	W	т	е	Standard quantity[pcs] Taping
MEHK2012H	2.0 ± 0.2 (0.079 ± 0.008)	1.2±0.2 (0.047±0.008)	0.8 max (0.031 max)	0.5 ± 0.3 (0.020 ± 0.012)	3000
MEKK2012H	2.0±0.2 (0.079±0.008)	1.2±0.2 (0.047±0.008)	1.0 max (0.039 max)	0.5±0.3 (0.020±0.012)	3000
MEKK2016H	2.0±0.2 (0.079±0.008)	1.6±0.2 (0.063±0.008)	1.0 max (0.039 max)	0.5±0.3 (0.020±0.012)	3000
MEKK2520H	2.5±0.2 (0.098±0.008)	2.0±0.2 (0.079±0.008)	1.0 max (0.039 max)	0.65±0.3 (0.026±0.012)	3000
				•	Unit:mm(inch)

for General Electronic Equipment

PARTS NUMBER

MEHK2012H type [Thickness:0.8mm max.]									
			Manala at the device of a		Self-resonant	DO Desistence	Rated current	※) [mA](max.)	Manager
	Parts number	EHS N	Nominal inductance [μΗ]	Inductance tolerance	frequency [MHz](min.)	DC Resistance [Ω](max.)	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
	MEHK2012HR47M	RoHS	0.47	+20%	-	0.035	4 100	3 700	1

MEKK2012H type [Thickness:1.0mm max.]

		Nominal inductance		Self-resonant	DC Besisteres	Rated current	※) [mA](max.)	Measuring
Parts number	EHS	[µ H]	Inductance tolerance	frequency [MHz](min.)		Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]
MEKK2012HR47M	RoHS	0.47	±20%	-	0.030	4,500	4,200	1

MEKK2016H type [Thickness: 1.0mm max.]

Newly of Sect		Manala at the device of a		Self-resonant	DO Desistence	Rated current 💥) [mA](max.)		Manager	
Parts number	Parts number EHS Nom		[µ H] Inductance tolerance		DC Resistance [Ω](max.)	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	
MEKK2016HR47M	RoHS	0.47	±20%	-	0.026	5,300	4,700	1	
MEKK2016H1R0M	RoHS	1.0	±20%	-	0.048	4,000	3,500	1	
MEKK2016H2R2M	RoHS	2.2	±20%	-	0.100	2,300	2,300	1	

MEKK2520H type [Thickness:1.0mm max.]

Parts number	EHS	Nominal inductance [µ H]	Inductance tolerance	Self–resonant frequency [MHz] (min.)	DC Resistance [Ω](max.)	Rated current Saturation current Idc1	※) [mA](max.) Temperature rise current Idc2	Measuring frequency[MHz]
MEKK2520H1R0M	RoHS	1	±20%	-	0.039	4,400	3,800	1

*) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

*) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

XX) The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

※) Idc2 Measurement board data Material:FR4

Board dimensions: $100 \times 50 \times 1.6t$ mm Pattern dimensions: 45×45 mm (Double side board) Pattern thickness: $70 \,\mu$ m

METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL[™] ME SERIES ∕ MCOIL[™] ME-H SERIES)

PACKAGING

①Minimum Quantity							
Turne	Standard Quantity [pcs]						
Туре	Tape & Reel						
MEHK2012	3000						
MEKK2012	3000						
MEKK2016	3000						
MEKK2520	3000						

2 Tape Material



$\textcircled{3}\mathsf{Taping dimensions}$

Embossed tape 8mm wide (0.315 inches wide)



Туре	Chip	cavity	Insertion pitch	Tape thickness	
Туре	A	В	F	Т	К
MEHK2012	1.45±0.1	2.25 ± 0.1	4.0 ± 0.1	0.25 ± 0.05	1.1 ± 0.1
	(0.057±0.004)	(0.089 ± 0.004)	(0.157 ± 0.004)	(0.009 ± 0.002)	(0.043 ± 0.004)
MEKK2012	1.45±0.1	2.25 ± 0.1	4.0±0.1	0.25 ± 0.05	1.1±0.1
	(0.057±0.004)	(0.089 ± 0.004)	(0.157±0.004)	(0.009 ± 0.002)	(0.043±0.004)
MEKK2016	1.9±0.1	2.45±0.1	4.0±0.1	0.25 ± 0.05	1.2±0.1
	(0.075±0.004)	(0.097±0.004)	(0.157±0.004)	(0.009 ± 0.002)	(0.047±0.004)
MEKK2520	2.4 ± 0.1	2.9±0.1	4.0±0.1	0.25 ± 0.05	1.1±0.1
	(0.094 ± 0.004)	(0.114±0.004)	(0.157±0.004)	(0.009 ± 0.002)	(0.043±0.004)
	•	•	•		Unit:mm(inch)

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This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL[™] ME SERIES ∕ MCOIL[™] ME-H SERIES)

RELIABILITY DATA

1. Operating Temperature Range				
Specified Value	ME series	-40~+125°C		
	ME-H series	-40~ + 125 C		
Test Methods and Remarks	Including self-generated heat			

2. Storage Tempera	2. Storage Temperature Range					
Specified Value	ME series					
	ME-H series	$-40 \sim +85^{\circ}$ C				
Test Methods and Remarks	0 to 40°C for the product with taping.					

3. Rated current			
Specified Value	ME series		
	ME-H series	Within the specified tolerance	

4. Inductance				
Crassifierd Malue	ME series			
Specified Value	ME-H series		Within the specified tolerance	
Test Methods and	Measuring equipment : LCR Meter (HP 4		294A or equivalent)	
Remarks	Measuring frequency	: 1MHz、0.5V		

5. DC Resistance	5. DC Resistance			
Specified Value	ME series			
Specified value	ME-H series	Within the specified tolerance		
Test Methods and Remarks	Measuring equipment : DC ohmmeter (HIOKI 3227 or equivalent)		

6. Self resonance frequency		
Specified Value	ME series	
Specified Value	ME-H series	

7. Temperature characteristic			
Specified Value	ME series	Industance change, Within ± 150	
Specified Value	ME-H series	Inductance change : Within $\pm 15\%$	
Test Methods and Remarks	Measurement of inductance shall be taken at temperature range within $-40^{\circ}C \sim +125^{\circ}C$. With reference to inductance value at $+20^{\circ}C$., change rate shall be calculated.		

8. Resistance to fle	xure of substrate				
Specified Value	ME series		NL L		
Specified value	ME-H series		No damage		
Test Methods and Remarks	The test samples shall be s until deflection of the test Test board size Test board material Solder cream thickness		mm Force Rod 10 20		

9. Insulation resistance : between wires			
0	ME series		
Specified Value	ME-H series		
10. Insulation resist	ance : between wire and over-coating		
0 10 10 1	ME series		
Specified Value	ME-H series		
11. Withstanding vol	tage : between wire and over-coating		
Specified Value	ME series		
Specified Value	ME-H series		

12. Adhesion of terr	12. Adhesion of terminal electrode				
Specified Value	ME series		Na alexandra l'ha		
Specified value	ME-H series		No abnormality.		
	The test samples shall be soldered to the test		st board by the reflow.		
Test Methods and	Applied force	: 10N to X and	Y directions.		
Remarks	Duration	: 5s.			
Solder cream thickness : 0.12mm.					

13. Resistance to vibration				
Specified Value		IE series		Inductance change : Within $\pm 10\%$
		ME-H series		No significant abnormality in appearance.
	The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions.			•
		Frequency Range	10~55Hz	
Test Methods and		Total Amplitude	1.5mm (May	y not exceed acceleration 196m/s ²)
Remarks		Sweeping Method	10Hz to 55H	Hz to 10Hz for 1min.
		Time	X Y Z	For 2 hours on ach X, Y, and Z axis.
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			der the standard condition after the test, followed by the measurement within 48hrs.

14. Solderability			
Specified Value	ME series		
	ME-H series		At least 90% of surface of terminal electrode is covered by new solder.
T . M .: 1	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux : Methanol solution containing rosin 25%.		
Test Methods and Remarks	Solder Temperature	245±5°C	
	Time	5±0.5 sec.	
	XImmersion depth : All sid	es of mounting ter	rminal shall be immersed.

15. Resistance to soldering heat			
Specified Value	ME series	Inductance change : Within $\pm 10\%$	
Specified value	ME-H series	No significant abnormality in appearance.	
Test Methods and Remarks	The test sample shall be exposed to reflow oven at 230°C for 40 seconds, with peak temperature at $260+0/-5$ °C for 5 seconds, 2 time Test board material : Glass epoxy-resin Test board thickness : 1.0mm Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		



16. Thermal shock					
Specified Value	ME series			Inductance change : V	Vithin $\pm 10\%$
Specified value	ME-H series			No significant abnorm	ality in appearance.
Test Methods and Remarks	time by s Step 1 2	time by step 1 to step 4 as shown in below to Conditions of 1 cycle Step Temperature (°C) 1 -40±3		ble in sequence. The tr Duration (min) 30±3 Within 3	he test samples shall be placed at specified temperature for specified emperature cycle shall be repeated 100 cycles.
	3	+85±2 Room temperature		30±3 Within 3	
	Recovery	· · · ·	nder the		fter the test, followed by the measurement within 48hrs.

17. Damp heat			
Specified Value	ME series		Inductance change : Within $\pm 10\%$
Specified value	ME-H series		No significant abnormality in appearance.
T . M	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.		
Test Methods and Remarks	Temperature	60±2°C	
Remarks	Humidity	90~95%RH	
	Time	500+24/-0 hour	
	Recovery : At least 2	hrs of recovery under th	ne standard condition after the test, followed by the measurement within 48hrs.

18. Loading under damp heat			
Specified Value	ME series		Inductance change : Within $\pm 10\%$
Specified value	ME-H series		No significant abnormality in appearance.
Test Methods and	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.		
Remarks	Temperature	60±2°C	
Remarks	Humidity	90~95%RH	
	Applied current	Rated current	
	Time	500+24/-0 hour	
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		

19. Low temperature life test			
Specified Value	ME series		Inductance change : Within $\pm 10\%$
Specified Value	ME-H series		No significant abnormality in appearance.
	The test samples sha	III be soldered to the test	board by the reflow. After that, the test samples shall be placed at test conditions as shown
Test Methods and in below table.			
Remarks	Temperature	-40±2°C	
	Time	500+24/-0 hour	
Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48H		e standard condition after the test, followed by the measurement within 48hrs.	

20. High temperature life test			
Specified Value	ME series		Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.
Specified value	ME-H series		
	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as show		
Test Methods and in below table.			
Remarks	Temperature	125±2°C	
	Time	500+24/-0 hour	
Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement		ne standard condition after the test, followed by the measurement within 48hrs.	

21. Loading at high temperature life test			
Specified Value	ME series		
	ME-H series		



22. Standard condition		
Specified Value	ME series	Standard test condition : Unless otherwise specified, temperature is $20\pm15^\circ\!C$ and $65\pm20\%$ of relative humidity.
	ME-H series	When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of $20\pm2^{\circ}$ C of temperature, $65\pm5\%$ relative humidity. Inductance is in accordance with our measured value.



PRECAUTIONS

1. Circuit Design	
Precautions	 Operating environment The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

2. PCB Design		
Precautions	 ◆Land pattern design 1. Please refer to a recommended land pattern. 	
Technical considerations	 Land pattern design Surface Mounting Mounting and soldering conditions should be checked beforehand. Applicable soldering process to this products is reflow soldering only. 	

3. Considerations for automatic placement			
Precautions	 Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand. 		
Technical	◆Adjustment of mounting machine		
considerations	1. When installing products, care should be taken not to apply distortion stress as it may deform the products.		

Precautions	 Reflow soldering Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. The product shall be used reflow soldering only. Please do not add any stress to a product until it returns in normal temperature after reflow soldering. Lead free soldering When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering
	heat, soldering etc sufficiently.
Technical considerations	♦Reflow soldering If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. Recommended reflow condition (Pb free solder) 300 150~180°C 150~180°C 150~180°C 30±10sec 30±10sec 230°C min Heating Time [sec] Heating Time [sec] Additional products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

5. Cleaning	
Precautions	 ♦ Cleaning conditions 1. Washing by supersonic waves shall be avoided.
Technical considerations	 Cleaning conditions 1. If washed by supersonic waves, the products might be broken.

6. Handling	
Precautions	 Handling Keep the product away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations) When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations Please do not give the product any excessive mechanical shocks. Please do not add any shock and power to a product in transportation. Pick-up pressure Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. Packing Please avoid accumulation of a packing box as much as possible.
Technical considerations	 Handling There is a case that a characteristic varies with magnetic influence. Breakaway PC boards (splitting along perforations) The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs. Mechanical considerations There is a case to be damaged by a mechanical shock. There is a case to be broken by the handling in transportation. Pick-up pressure Damage and a characteristic can vary with an excessive shock or stress. Packing If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.

7. Storage conditions	
Precautions	 Storage To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions
Technical considerations	 Storage Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.



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